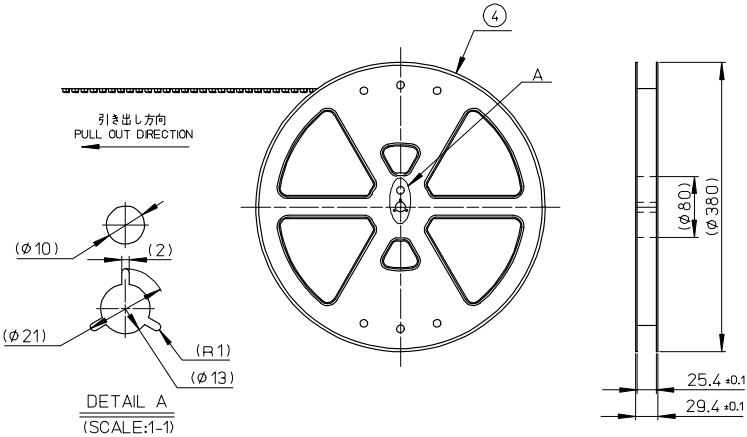
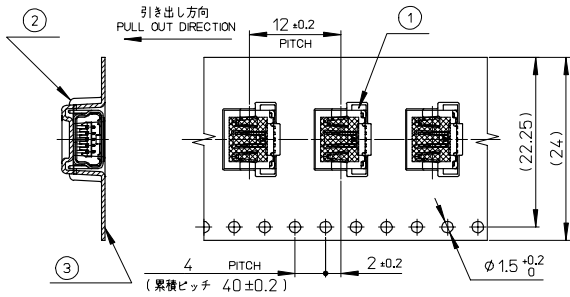


10 9 8 7 6 5 4 3 2 1



DETAIL A
(SCALE:1-1)

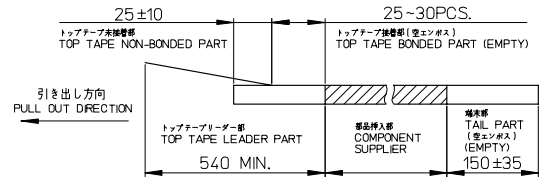


エンボステープ内の製品の向き
DIRECTION OF PRODUCT
IN EMBOSSED TAPE
(SCALE:2-1)

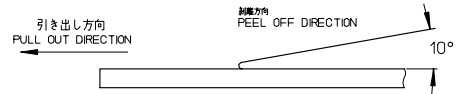
①	コネクタ CONNECTOR
②	エンボステープ EMBOSSED TAPE
③	トップテープ TOP TAPE
④	リール REEL

注記

- コネクタ詳細は SD-51387-006を参照下さい。
REFER TO SD-51387-006
- 梱包数量: 1200個/リール
NUMBER OF CONNECTOR : 1200 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: $0.6 \pm 0.35N$ ($60 \pm 35gf$)
<剥離速度: 300mm/min (参考)> (剥離方向は下図参照)
PEEL-OFF FORCE OF TOP TAPE : $0.6 \pm 0.35N$ ($60 \pm 35gf$)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
<PEEL-OFF SPEED : 300mm/min (REF.)>

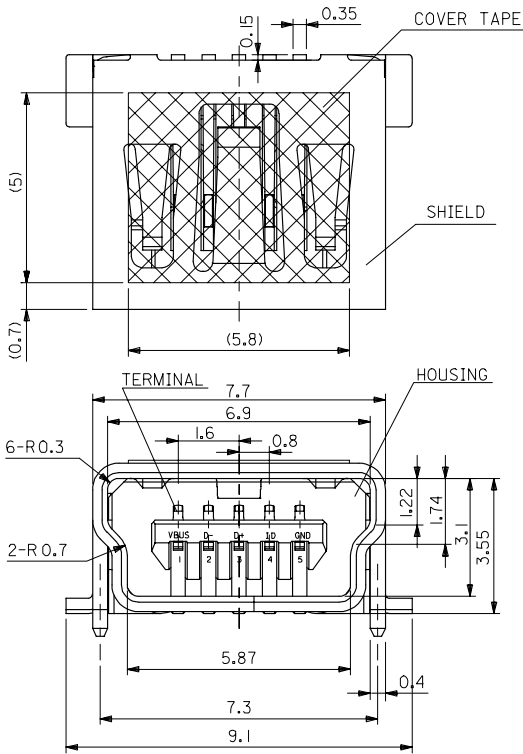


- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE : POLYPROPYLENE
トップテープ : ポリエステル, ポリエチレン
TOP TAPE : POLYESTER, POLYETHYLENE
リール : ポリスチレン
REEL : POLYSTYREN

51387-0530	51387-***0
製品番号 MATERIAL No.	MODEL No.

新機种発売 IEC NO. J2005-0570 DRAWN BY MSHINYAMA 2004/08/30 CHECKED BY HTAKASE 2004/08/30 APPROVED BY JMIYAZAWA 2004/09/02 DESCRIPTION 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	EMBOSSED TAPE PKG. FOR 51387-0539 -LEAD FREE-		
	30 OVER	±0.3	APPROVED BY	DATE	MOLEX INCORPORATED		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
				SEE CHART	SD-51387-005	1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1



注記
NOTES

1. 材質

MATERIAL

ハウジング: 耐熱樹脂 ガラス充填, 黒色, UL94V-0
 HOUSING: HEAT RESISTANT PLASTIC,
 GLASS FILLED, BLACK, UL94V-0
 ターミナル: 銅合金 (t=0.25)
 TERMINAL: COPPER ALLOY (t=0.25)
 シールド: 銅合金 (t=0.4)
 SHIELD: COPPER ALLOY (t=0.4)
 カバー テープ: ポリイミド (t=0.08)
 COVER TAPE: POLYIMIDE (t=0.08)

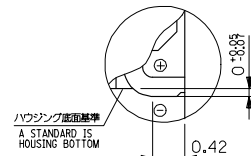
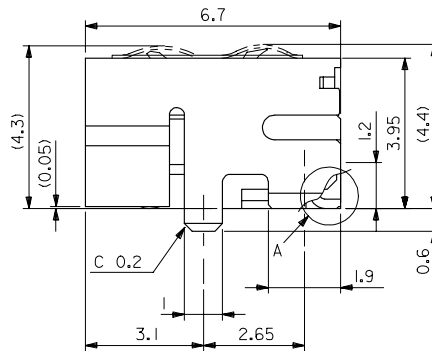
2. メッキ仕様

PLATING

ターミナル
TERMINAL

接点部: 金メッキ
CONTACT AREA: GOLD
 半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
 下地部: ニッケルメッキ
UNDER PLATING: NICKEL
 シールド
SHIELD
 : 錫メッキ
: TIN
 下地部: ニッケル
UNDER PLATING: NICKEL

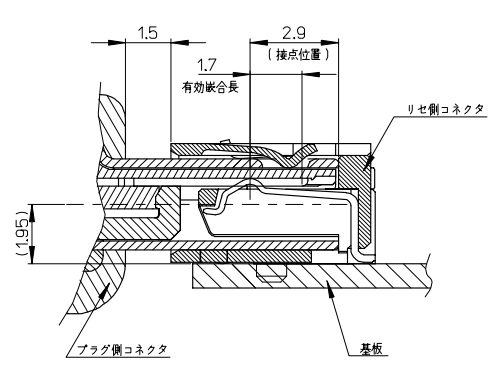
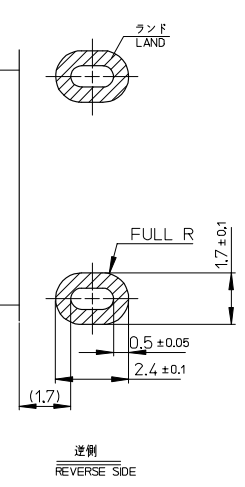
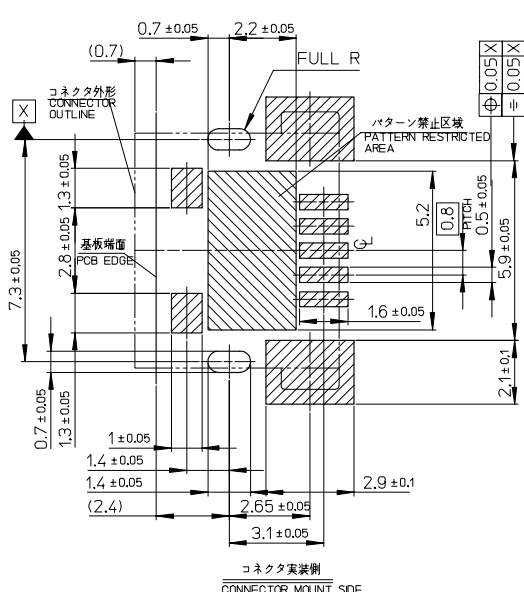
3. 平坦度は 0.1 mm MAX.
 COPLANARITY 0.1mm MAX.



DETAIL A
 (SCALE 20:1)

5	51387-0539
極数 CKT.	製品番号 MATERIAL NO.

REVISED EC NO: J2007-2931 2007/04/19 DRAWN: AOYAGI 2007/04/23 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE- MOLEX INCORPORATED DOCUMENT NO. SD-51387-006 SHEET NO. 1 OF 2		
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/06/18			
	30 OVER	±0.3	APPROVED BY JMIYAZAW	DATE 04/06/18			
ANGULAR	±3 °	MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



推奨基板寸法 (SCALE 8:1)
RECOMMENDED PCB PATTERN LAYOUT

REVISED EC NO: J2007-2931 DRAWN: AOYAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY YSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASSY (REFLOW DIP TYPE) -LEAD FREE- MOLEX INCORPORATED		
	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/06/18			
	30 OVER	± 0.3	APPROVED BY JMIYAZAW	DATE 04/06/18			
	ANGULAR	± 3 °	MATERIAL NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1					
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			DOCUMENT NO. SD-51387-006	SHEET NO. 2 OF 2